

•General Description

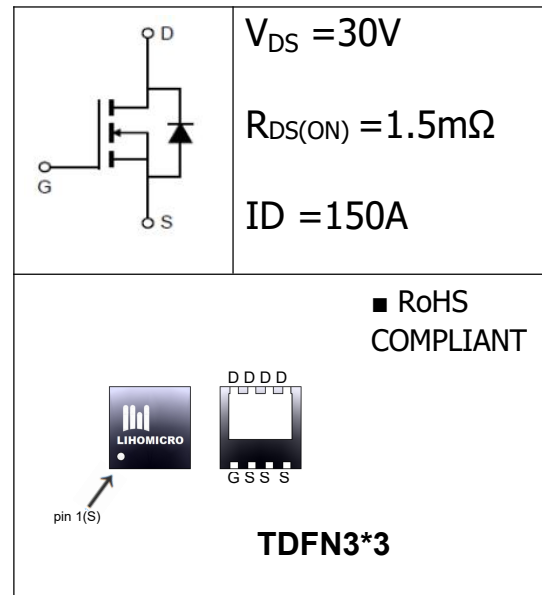
The SGT MOSFET LH015N03S has the low $R_{DS(on)}$, low gate charge, fast switching and excellent avalanche characteristics. This device is suitable for fast charge and lighting.

•Features

- Fast switching
- Low $R_{DS(on)}$ & FOM
- Low Gate Charge

•Application

- PD Charger
- Power Supplies
- DC/DC Converters


•Ordering Information:

Part Number	LH015N03S
Package	TDFN3*3
Basic Ordering Unit (pcs)	5000
Normal Package Material Ordering Code	LH015N03STD3-TDFN3*3-TAP
Halogen Free Ordering Code	LH015N03STD3-TDFN3*3-TAP-HF

•Absolute Maximum Ratings (TC =25°C)

PARAMETER	SYMBOL	Value	UNIT
Drain-Source Breakdown Voltage	BV_{DSS}	30	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current , $T_C = 25^\circ C$	I_D	150	A
Pulsed drain current (TC = 25°C, tp limited by Tjmax) ¹	I_D pulse	300	A
Single Pulse Avalanche Energy ²	E_{AS}	306	mJ
Power Dissipation(TC=25°C)	P_D	68	W
Operating Temperature	T_J	-55~+150	°C
Storage Temperature	T_{STG}	-55~+150	°C

●Electronic Characteristics

PARAMETER	SYMBOL	TEST CONDITION	MIN	TYP	MAX	UNIT
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=250\mu A$	30	--	--	V
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	1.2	--	2.2	V
Drain-source On Resistance ³	$R_{DS(ON)}$	$V_{GS}=10V, I_D=20A$	--	1.5	2.4	mΩ
		$V_{GS}=4.5V, I_D=10A$	--	3.2	3.8	
Drain-Source Leakage Current	I_{DSS}	$V_{DS}=24V, V_{GS}=0V, T_J=25^\circ C$	--	--	1	μA
		$V_{DS}=24V, V_{GS}=0V, T_J=85^\circ C$	--	--	5	
Gate-Source Leakage Current	I_{GSS}	$V_{GS}=\pm 20, V_{DS}=0V$	--	--	±100	nA
Input Capacitance	C_{iss}	$V_{GS}=0V,$ $V_{DS}=15V$ $f=1.0MHz$	--	3483	--	pF
Output Capacitance	C_{oss}		--	1810	--	
Reverse transfer Capacitance	C_{rss}		--	190	--	
Turn -Off Delay Time	$T_d(off)$	$V_{GS}=10V,$ $I_D=20A$ $R_G=3.3\Omega$	--	56	--	ns
Turn-on delay time	$T_d(on)$		--	10	--	
Rise time	T_r		--	6.2	--	
Fall time	T_f		--	8.2	--	
Total Gate Charge	Q_g	$I_D=20A,$ $V_{DS}=15V$ $V_{GS}=10V$	--	40	---	nC
Gate-to-Source Charge	Q_{gs}		--	9.8	--	
Gate-to-Drain Charge	Q_{gd}		--	6.8	---	
Continuous Diode Forward Current	I_S	--	--	--	150	A
Pulsed Diode Forward Current	I_{SM}	--	--	--	300	A
Diode Forward Voltage	V_{SD}	$T_J=25^\circ C, I_S=10.0A$ $V_{GS}=0V$	--	--	1.2	V

●Thermal Characteristics

PARAMETER	SYMBOL	MAX	UNIT
Thermal Resistance Junction-case	R_{thJC}	1.84	°C/W
Thermal Resistance Junction-ambient	R_{thJA}	50	°C/W

Notes:

- 1.Repetitive Rating: Pulse width limited by maximum junction temperature.
2. $I_{AS}=35A, V_{DD}=15V, R_G=25\Omega$, Starting $T_J=25^\circ C$
3. Pulse Test : Pulse width $\leq 300\mu s$, Duty cycle $\leq 2\%$

• **Typical Characteristics**

Fig.1 Typical Output Characteristics

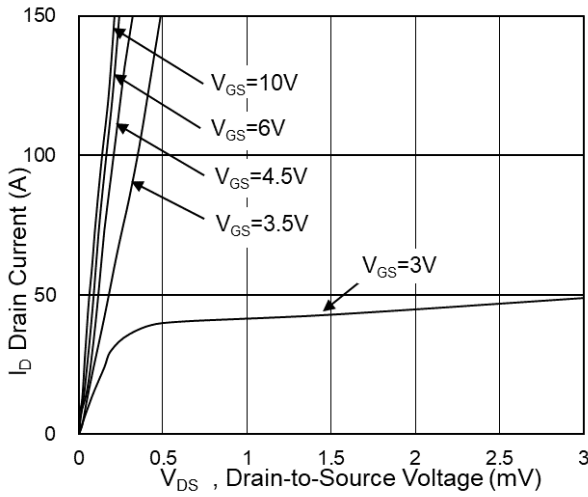


Fig.2 On-Resistance vs G-S Voltage

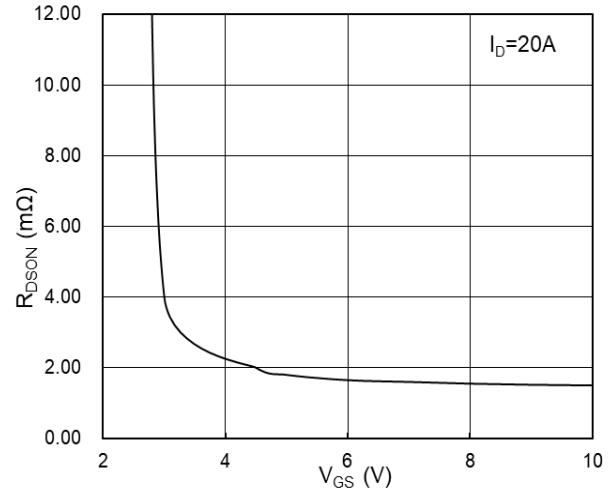


Fig.3 Source Drain Forward Characteristics

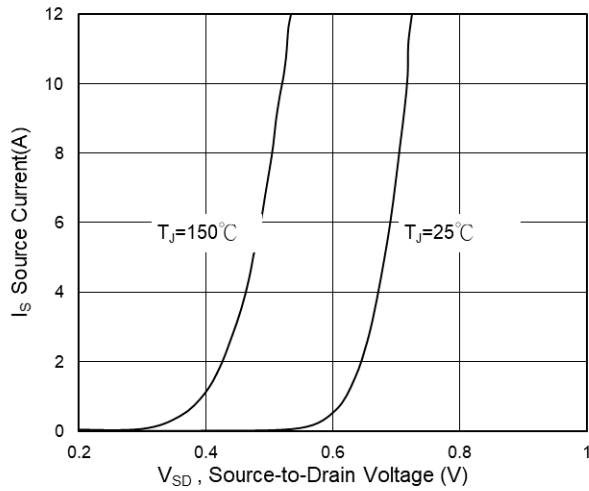


Fig.4 Capacitance

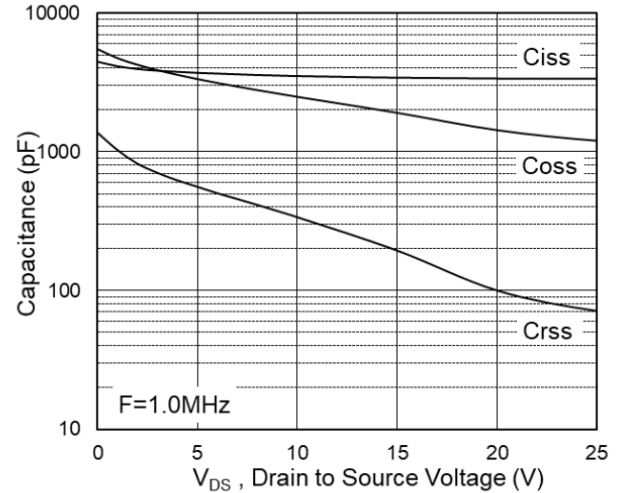


Fig.5 Normalized V_GS(th) vs T_J

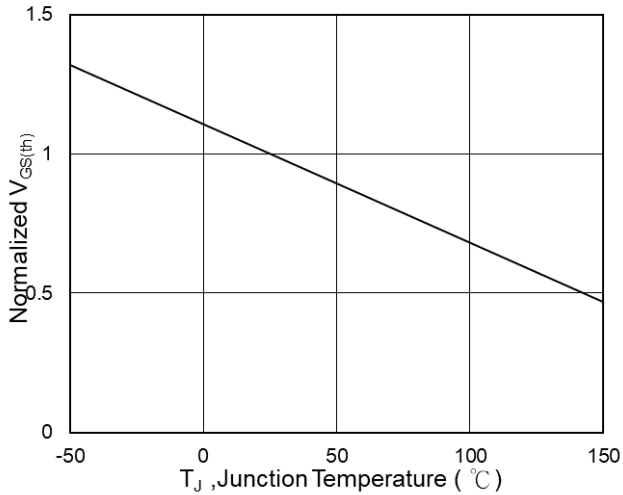
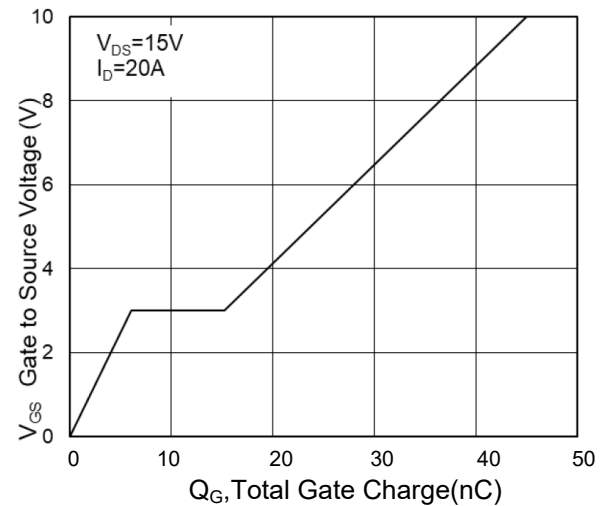


Fig.6 Gate-Charge Characteristics



● **Typical Characteristics**(cont.)

Fig.7 Normalized RDSON vs TJ

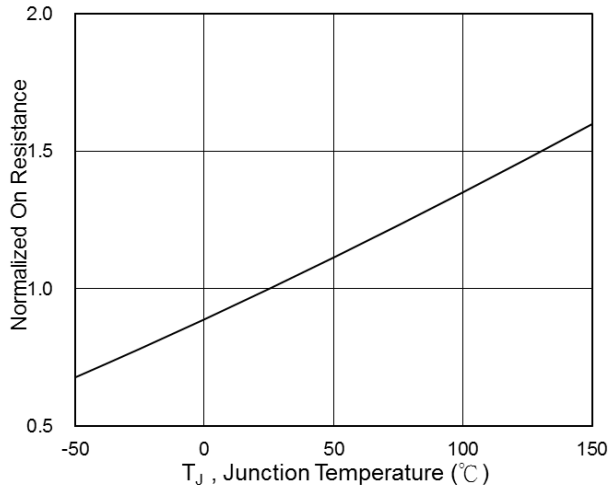


Fig.8 Safe Operating Area

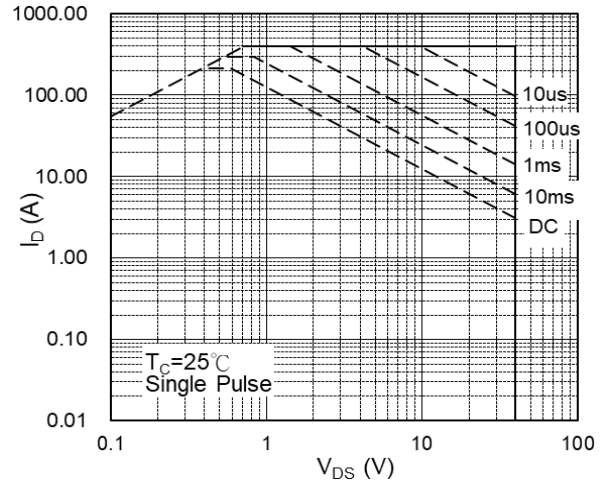
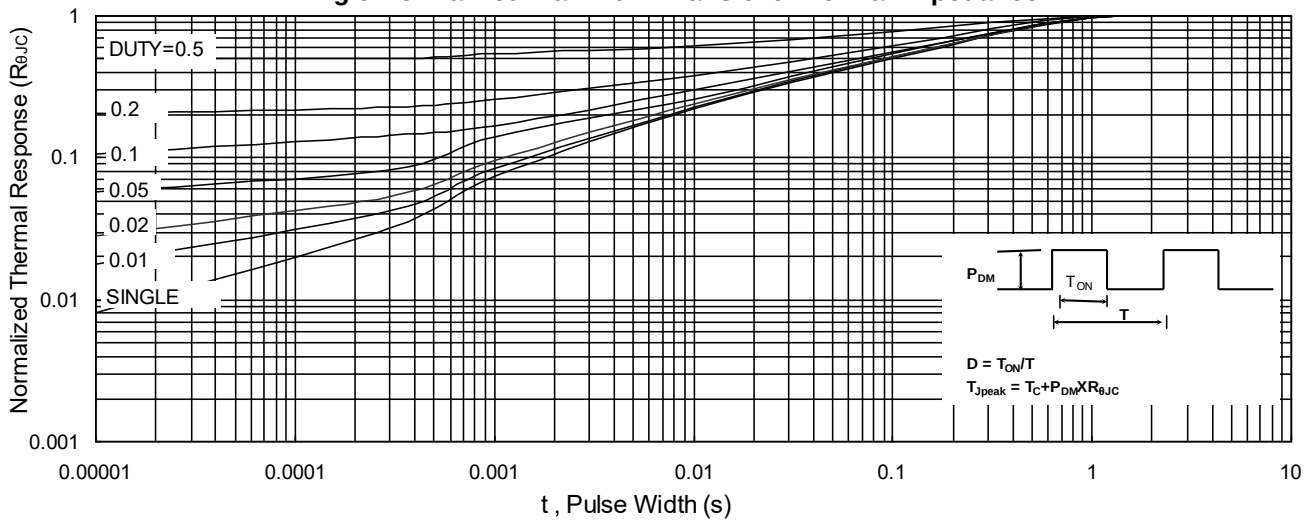


Fig.9 Normalized Maximum Transient Thermal Impedance



• Test Circuits & Waveforms

Fig1.EAS test Circuits

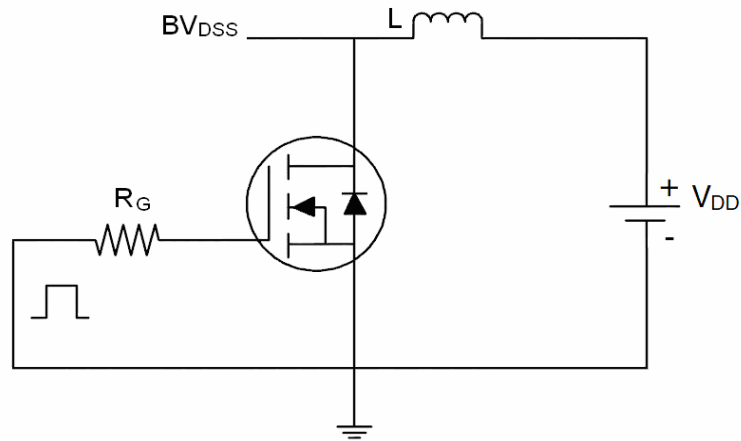


Fig2.Gate charge test Circuit

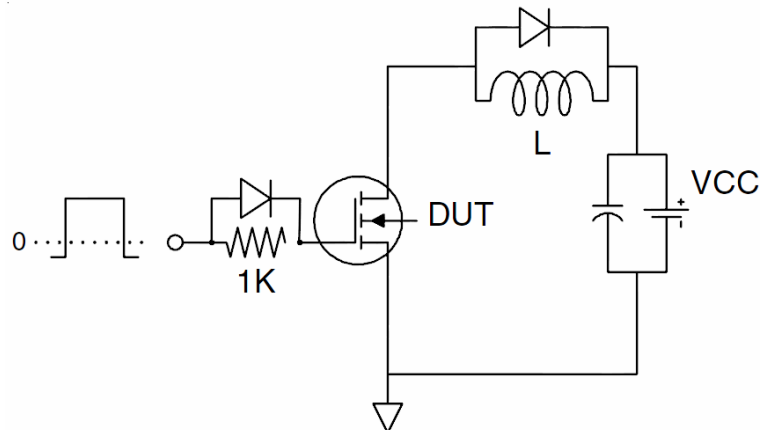
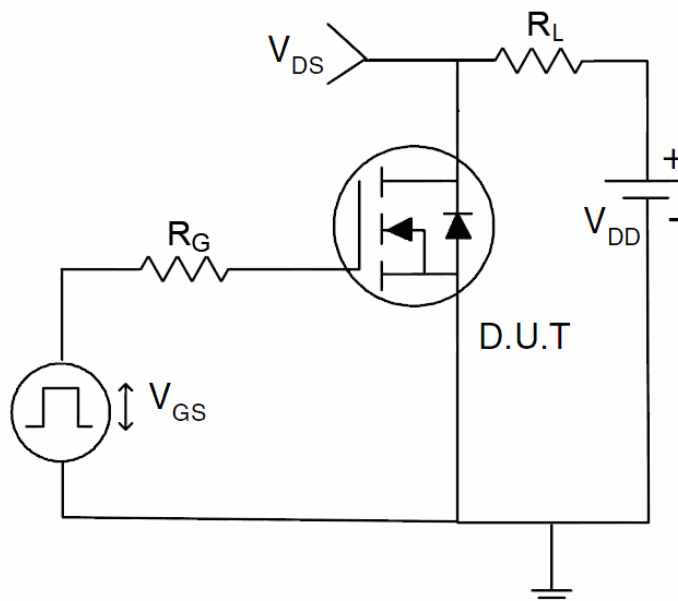


Fig3.Switch Time Test Circuit



•Dimensions (TDFN3*3)

Unit: mm

SYMBOL	min	max	SYMBOL	min	max
A	0.75	1.05	E2	2.05	2.25
b	0.30	0.40	e	0.65BSC	
c	0.15	0.25	K	0.25	0.45
D	3.20	3.40	A1	0.00	0.05
D2	2.65	2.85			
L	0.40	0.60			
E	3.20	3.40			

